

Maximum Ratings / Höchstzulässige Werte

Parameter	Condition	Symbol	Datasheet values	Unit
			max.	

Transistor Inverter
Transistor Wechselrichter

Collector-emitter break down voltage Kollektor-Emitter-Sperrspannung		V_{CE}	600	V
DC collector current Kollektor-Dauergleichstrom	$T_J=150^{\circ}\text{C}$ $T_h=80^{\circ}\text{C}$, $T_c=80^{\circ}\text{C}$	I_C	7 10, limited by wires	A
Repetitive peak collector current Periodischer Kollektorspitzenstrom	$t_p=1\text{ms}$ $T_h=80^{\circ}\text{C}$	I_{cpuls}	19	A
Power dissipation per IGBT Verlustleistung pro IGBT	$T_J=150^{\circ}\text{C}$ $T_h=80^{\circ}\text{C}$, $T_c=80^{\circ}\text{C}$	P_{tot}	24 37	W
Gate-emitter peak voltage Gate-Emitter-Spitzenspannung		V_{GE}	± 20	V
SC withstand time Kurzschlußverhalten	$T_J \leq 150^{\circ}\text{C}$ $V_{CE}=V_{CEBR}$	T_{SC}	10	us

Diode Inverter
Diode Wechselrichter

DC forward current Dauergleichstrom	$T_J=150^{\circ}\text{C}$ $T_h=80^{\circ}\text{C}$, $T_c=80^{\circ}\text{C}$	I_F	10, limited by wires 10, limited by wires	A
Repetitive peak forward current Periodischer Spitzenstrom	$t_p=1\text{ms}$ $T_h=80^{\circ}\text{C}$	I_{FRM}	32	A
Power dissipation per Diode Verlustleistung pro Diode	$T_J=150^{\circ}\text{C}$ $T_h=80^{\circ}\text{C}$, $T_c=80^{\circ}\text{C}$	P_{tot}	23 35	W

Thermal properties
Thermische Eigenschaften

max. Chip temperature max. Chiptemperatur		T_{jmax}	150	$^{\circ}\text{C}$
Storage temperature Lagertemperatur		T_{stg}	-40...+125	$^{\circ}\text{C}$
Operation temperature Betriebstemperatur		T_{op}	-40...+125	$^{\circ}\text{C}$

Insulation properties
Modulisolation

Insulation voltage Isolationsspannung	$t=1\text{min}$	V_{is}	4000	Vdc
Creepage distance Kriechstrecke			min 12,7	mm
Clearance Luftstrecke			min 12,7	mm

Characteristic values

Description	Symbol	Conditions					Datasheet values			Unit
		T(C°)	Other conditions (Rgon-Rgoff)	VGE(V) VGS(V)	VR(V) VCE(V) VDS(V)	IC(A) IFE(A) Id(A)	Min	Typ	Max	
Transistor Inverter, inductive load										
Transistor Wechselrichter										
Gate emitter threshold voltage Gate-Schwellenspannung	V _{GE(th)}	Tj=25°C Tj=125°C	VCE=VGE			2E-04	3	4	5	V
Collector-emitter saturation voltage Kollektor-Emitter Sättigungsspannung	V _{CE(sat)}	Tj=25°C Tj=125°C		15		5		2,21 2,61	2,9	V
Collector-emitter cut-off Kollektor-Emitter Reststrom	I _{CES}	Tj=25°C Tj=125°C		0	600				0,06 0,5	mA
Gate-emitter leakage current Gate-Emitter Reststrom	I _{GES}	Tj=25°C Tj=125°C		25	0				200	nA
Integrated Gate resistor Integriertes Gate Widerstand	R _{gint}							-		Ohm
Turn-on delay time Einschaltverzögerungszeit	t _{d(on)}	Tj=25°C Tj=125°C	Rgon=137 Ohm Rgoff=68,5 Ohm	15	300	5		18		ns
Rise time Anstiegszeit	t _r	Tj=25°C Tj=125°C	Rgon=137 Ohm Rgoff=68,5 Ohm	15	300	5		16		ns
Turn-off delay time Abschaltverzögerungszeit	t _{d(off)}	Tj=25°C Tj=125°C	Rgon=137 Ohm Rgoff=68,5 Ohm	15	300	5		245		ns
Fall time Fallzeit	t _f	Tj=25°C Tj=125°C	Rgon=137 Ohm Rgoff=68,5 Ohm	15	300	5		25		ns
Turn-on energy loss per pulse Einschaltverlustenergie pro Puls	E _{on}	Tj=25°C Tj=125°C	Rgon=137 Ohm Rgoff=68,5 Ohm	15	300	5		0,114		mWs
Turn-off energy loss per pulse Abschaltverlustenergie pro Puls	E _{off}	Tj=25°C Tj=125°C	Rgon=137 Ohm Rgoff=68,5 Ohm	15	300	5		0,112		mWs
Input capacitance Eingangskapazität	C _{ies}	Tj=25°C Tj=125°C	f=1MHz	0	25			0,264	0,317	nF
Output capacitance Ausgangskapazität	C _{oss}	Tj=25°C Tj=125°C	f=1MHz	0	25			0,029	0,035	nF
Reverse transfer capacitance Rückwirkungskapazität	C _{rss}	Tj=25°C Tj=125°C	f=1MHz	0	25			0,017	0,02	nF
Gate charge Gate Ladung	Q _{Gate}	Tj=25°C Tj=125°C		15	480	4		24	31	nC
Thermal resistance chip to heatsink per chip Wärmewiderstand Chip-Kühlkörper pro Chip	R _{thJH}		Thermal grease thickness≤50um Wärmeleitpaste Dicke≤50um λ = 0,61 W/mK					2,87 1,894		K/W
Coupled thermal resistance inverter diode-transistor Gekoppelte Wärmewiderstand Wechselrichter Diode-Transistor	R _{thJH}		Thermal grease thickness≤50um Wärmeleitpaste Dicke≤50um λ = 0,61 W/mK					TBD		K/W

Characteristic values

Characteristic values										
Description	Symbol	Conditions					Datasheet values			Unit
		T(C°)	Other conditions (Rgon-Rgoff)	VGE(V) VGS(V)	VR(V) VCE(V) VDS(V)	IC(A) IF(A) Id(A)	Min	Typ	Max	

Diode Inverter

Diode Wechselrichter

Diode forward voltage Durchlaßspannung	V _F	T _J =25°C T _J =125°C				5		1,38 1,08	2,1	V
Peak reverse recovery current Rückstromspitze	I _{RRM}	T _J =25°C T _J =125°C	Rgon=137 Ohm	15	300	5		8,2		A
Reverse recovery time Sperrverzögerungszeit	t _{rr}	T _J =25°C T _J =125°C	Rgon=137 Ohm	15	300	5		60		ns
Reverse recovered charge Sperrverzögerungsladung	Q _{rr}	T _J =25°C T _J =125°C	Rgon=137 Ohm	15	300	5		0,27		uC
Reverse recovered energy Sperrverzögerungsenergie	E _{rec}	T _J =25°C T _J =125°C	Rgon=137 Ohm	15	300	5		0,034		mWs
Thermal resistance chip to heatsink per chip Wärmewiderstand Chip-Kühlkörper pro Chip	R _{thJH}		Thermal grease thickness≤50um Wärmeleitpaste Dicke≤50um λ = 0,61 W/mK					3,03 2		K/W
Coupled thermal resistance inverter transistor-diode Gekoppelte Wärmewiderstand Wechselrichter Transistor-Diode	R _{thJH}		Thermal grease thickness≤50um Wärmeleitpaste Dicke≤50um λ = 0,61 W/mK					TBD		K/W

NTC-Thermistor

NTC-Widerstand

Rated resistance Nennwiderstand	R ₂₅	T _J =25°C	Tol. ±5%				20,9	22	23,1	kOhm
Deviation of R100 Abweichung von R100	D _{R/R}	T _c =100°C	R100=1503Ohm					2,9		%/K
Power dissipation given Epcos-Typ Verlustleistung Epcos-Typ angeben	P	T _J =25°C						210		mW
B-value B-Wert	B _(25/100)	T _J =25°C	Tol. ±3%					3980		K

Output inverter

Figure 1. Typical output characteristics

Output inverter IGBT
 $I_C = f(V_{CE})$

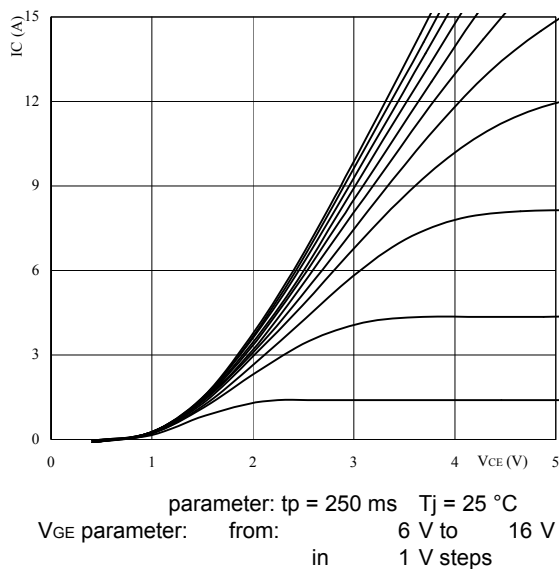


Figure 2. Typical output characteristics

Output inverter IGBT
 $I_C = f(V_{CE})$

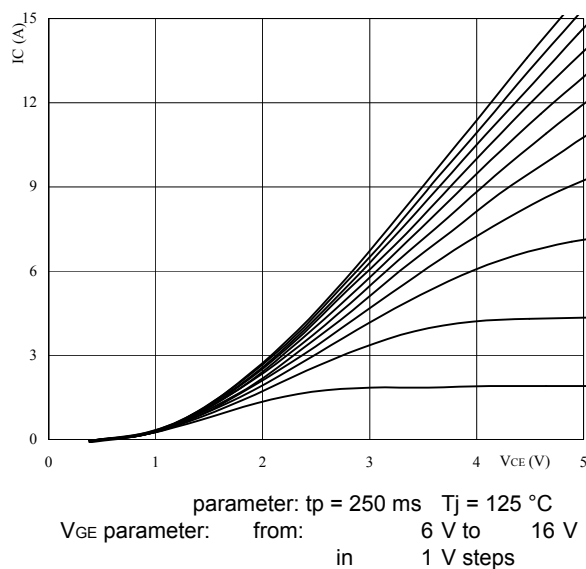


Figure 3. Typical transfer characteristics

Output inverter IGBT
 $I_C = f(V_{GE})$

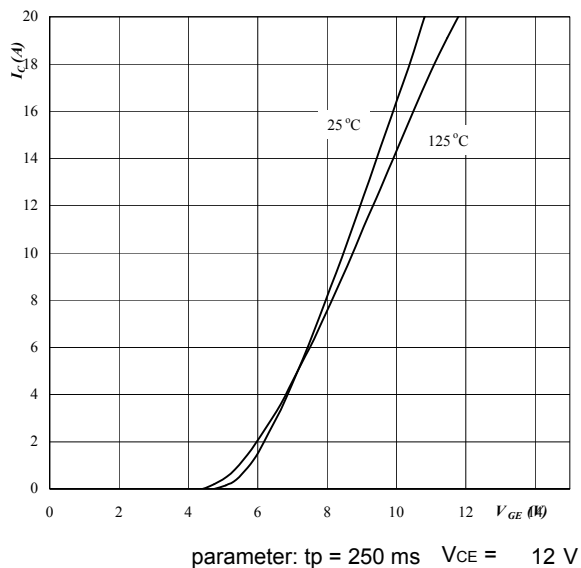
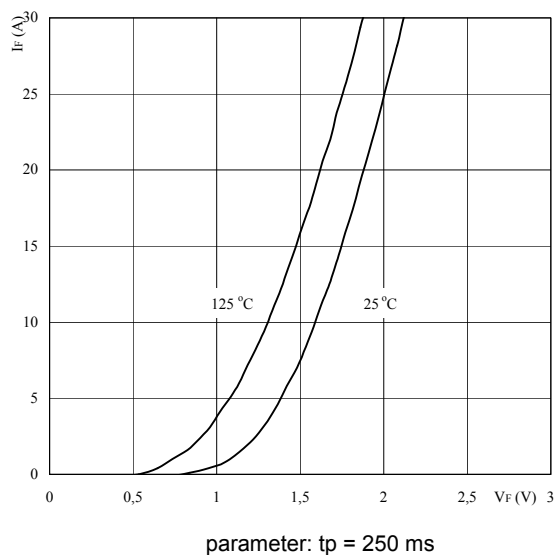


Figure 4. Typical diode forward current as a function of forward voltage

Output inverter FRED $I_F = f(V_F)$

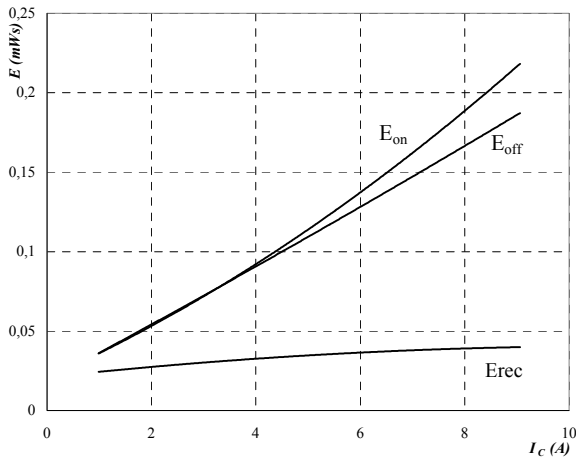


Output inverter

Figure 5. Typical switching energy losses as a function of collector current

Output inverter IGBT

$$E = f(I_c)$$



inductive load, $T_j = 125^\circ\text{C}$

$V_{CE} = 300\text{ V}$

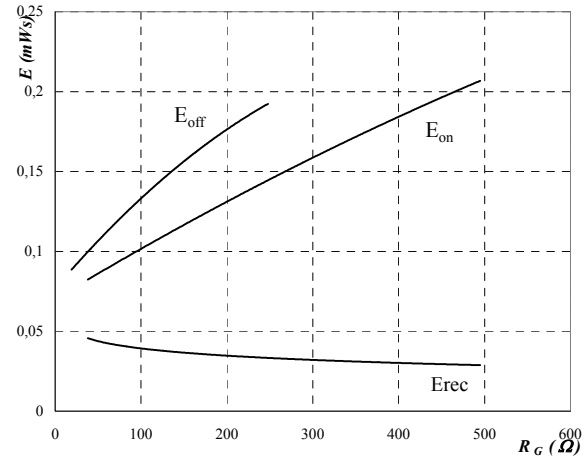
$V_{GE} = 15\text{ V}$

$R_{Gon} = 2 \cdot R_{Goff} = 137\text{ Ohm}$

Figure 6. Typical switching energy losses as a function of gate resistor

Output inverter IGBT

$$E = f(R_G)$$



inductive load, $T_j = 125^\circ\text{C}$

$V_{CE} = 300\text{ V}$

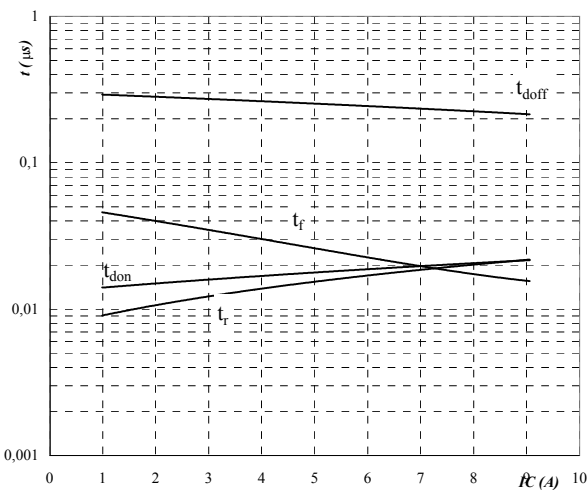
$V_{GE} = 15\text{ V}$

$I_c = 5\text{ A}$

Figure 7. Typical switching times as a function of collector current

Output inverter IGBT

$$t = f(I_c)$$



inductive load, $T_j = 125^\circ\text{C}$

$V_{CE} = 300\text{ V}$

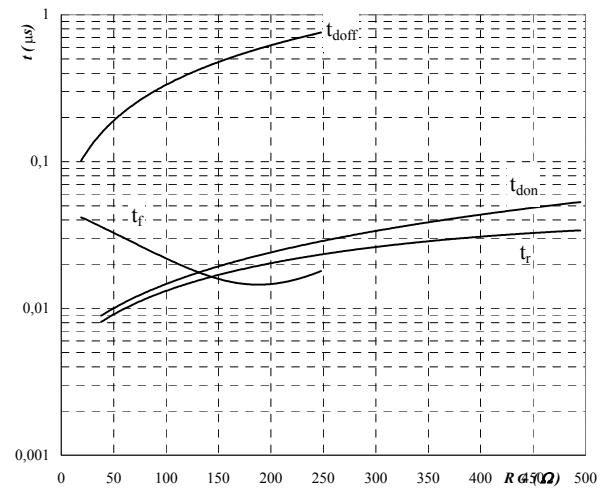
$V_{GE} = 15\text{ V}$

$R_{Gon} = 2 \cdot R_{Goff} = 137\text{ Ohm}$

Figure 8. Typical switching times as a function of gate resistor

Output inverter IGBT

$$t = f(R_G)$$



inductive load, $T_j = 125^\circ\text{C}$

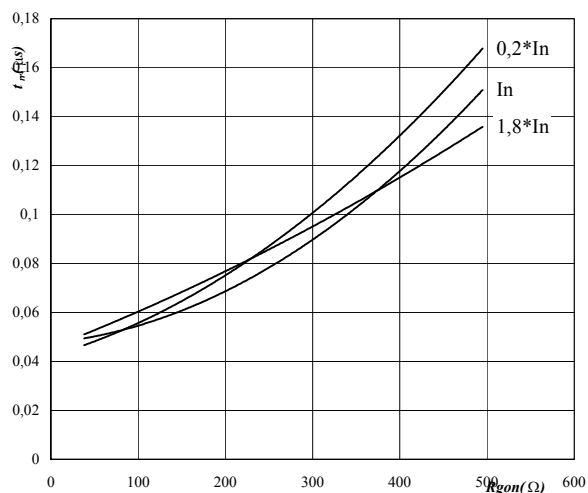
$V_{CE} = 300\text{ V}$

$V_{GE} = 15\text{ V}$

$I_c = 5\text{ A}$

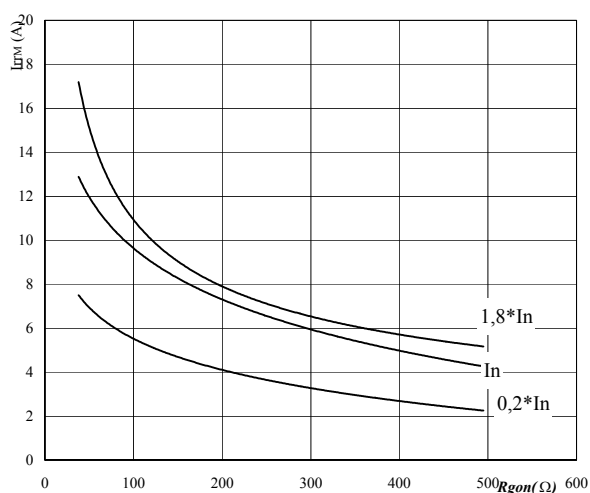
Output inverter

Figure 9. Typical reverse recovery time as a function of gate resistor
Output inverter FRED diode
 $t_{rr} = f(R_{gon})$



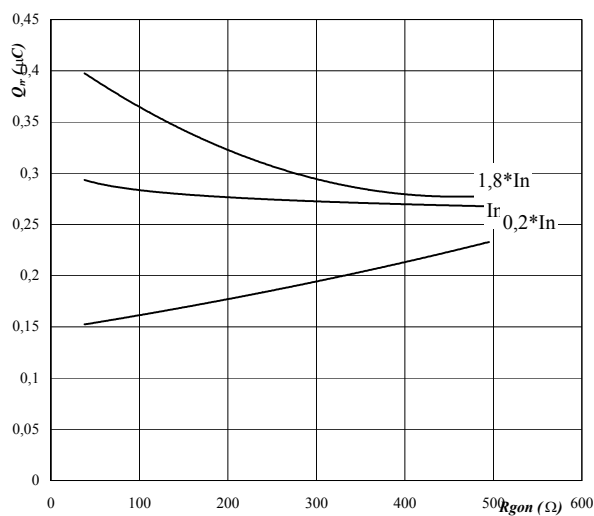
$T_j = 125^\circ C$
 $V_R = 300 V$
 $I_n = 5 A$

Figure 10. Typical reverse recovery current as a function of gate resistor
Output inverter FRED diode
 $I_{RRM} = f(R_{gon})$



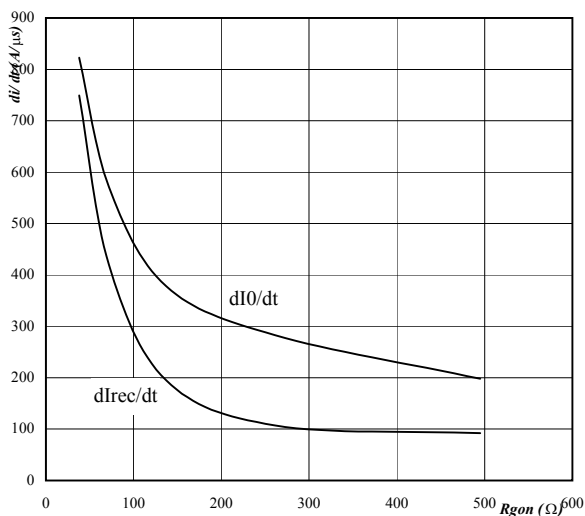
$T_j = 125^\circ C$
 $V_R = 300 V$
 $I_n = 5 A$

Figure 11. Typical reverse recovery charge as a function of gate resistor
Output inverter FRED diode
 $Q_{rr} = f(R_{gon})$



$T_j = 125^\circ C$
 $V_R = 300 V$
 $I_n = 5 A$

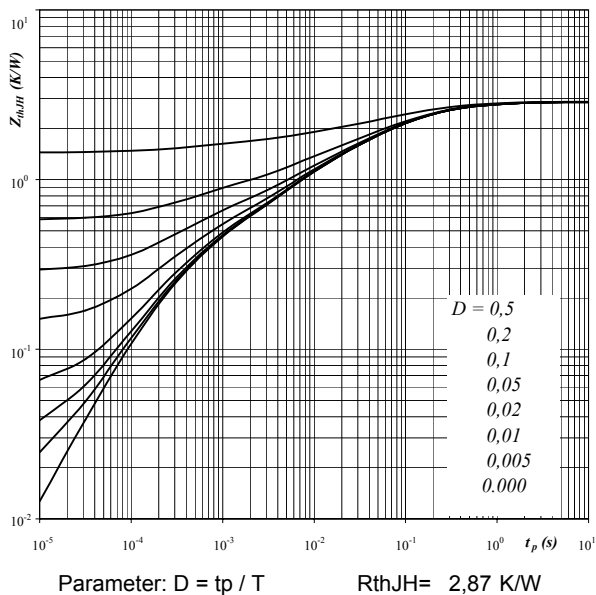
Figure 12. Typical diode peak rate of fall of forward and reverse recovery current as a function of gate resistor
Output inverter FRED diode
 $di_0/dt, dI_{rec}/dt = f(R_{gon})$



$T_j = 125^\circ C$
 $V_R = 300 V$
 $I_F = 5 A$

Output inverter

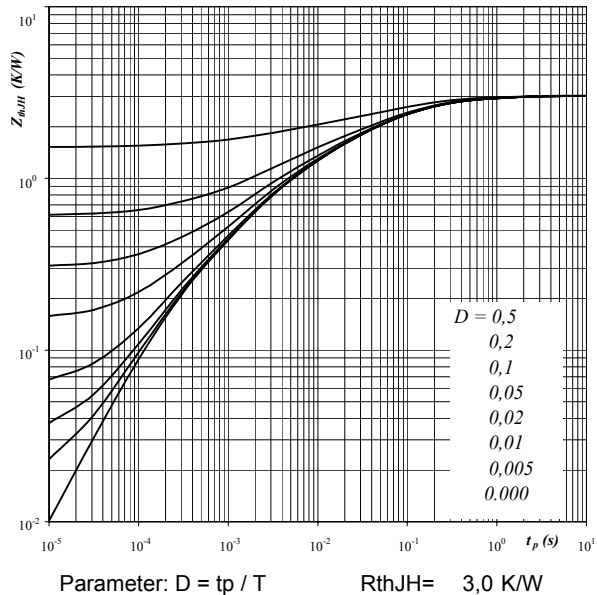
Figure 13. IGBT transient thermal impedance as a function of pulse width
 $Z_{thJH} = f(t_p)$



IGBT thermal model values

R (C/W)	Tau (s)
0,05	1,3E+01
0,31	6,6E-01
0,93	1,2E-01
0,73	2,7E-02
0,49	4,8E-03

Figure 14. FRED transient thermal impedance as a function of pulse width
 $Z_{thJH} = f(t_p)$



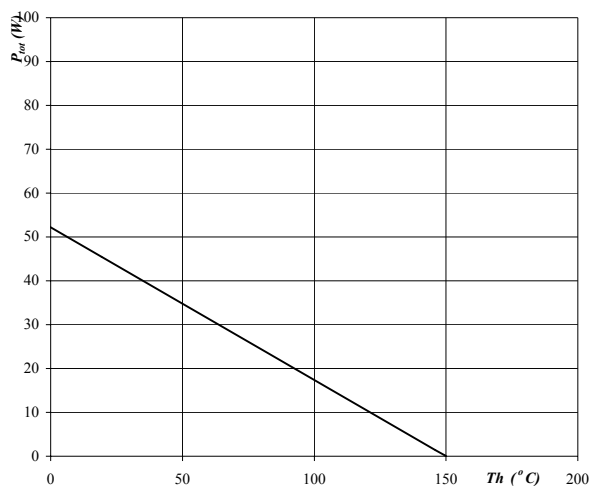
FRED thermal model values

R (C/W)	Tau (s)
0,04	4,2E+01
0,22	1,0E+00
0,84	1,4E-01
0,78	3,4E-02
0,61	7,4E-03

Output inverter

Figure 15. Power dissipation as a function of heatsink temperature

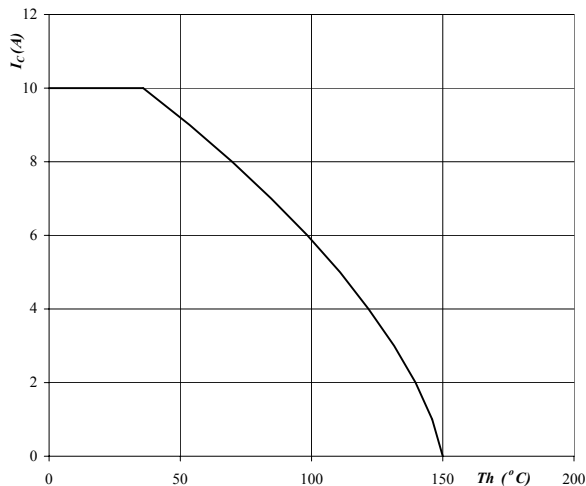
Output inverter IGBT
 $P_{tot} = f(T_h)$



parameter: $T_j = 150^\circ\text{C}$

Figure 16. Collector current as a function of heatsink temperature

Output inverter IGBT
 $I_c = f(T_h)$

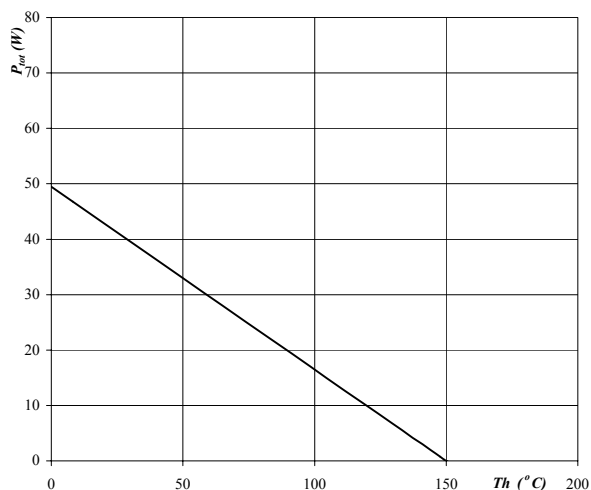


parameter: $T_j = 150^\circ\text{C}$

$V_{GE} = 15\text{ V}$

Figure 17. Power dissipation as a function of heatsink temperature

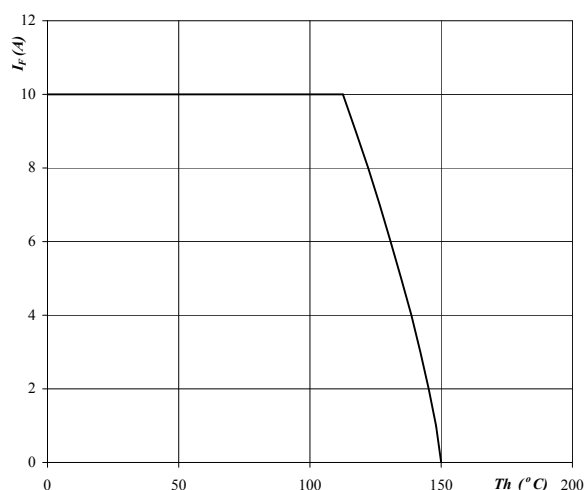
Output inverter FRED
 $P_{tot} = f(T_h)$



parameter: $T_j = 150^\circ\text{C}$

Figure 18. Forward current as a function of heatsink temperature

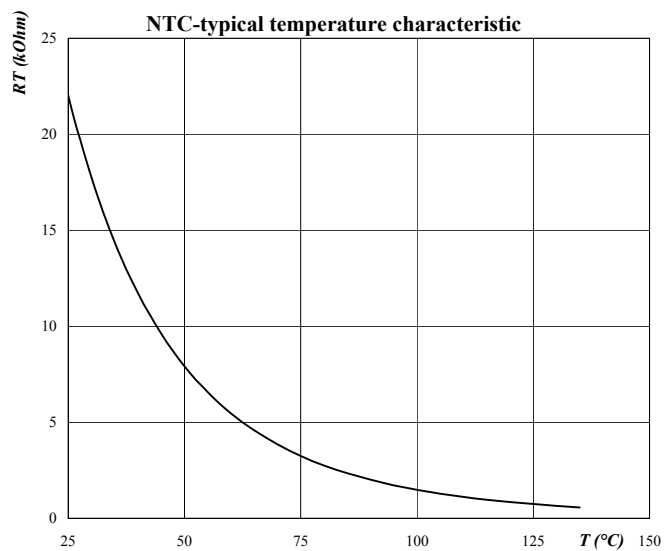
Output inverter FRED
 $I_F = f(T_h)$



parameter: $T_j = 150^\circ\text{C}$

Thermistor

**Figure 23. Typical NTC characteristic
as a function of temperature**
NTC
 $R_T = f(T)$



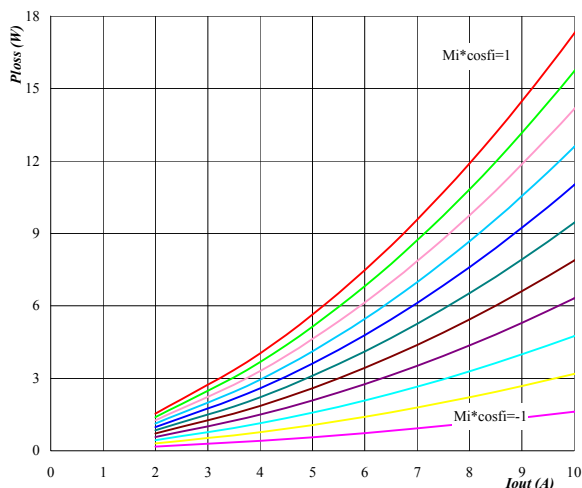
Output inverter application

General conditions: 3 phase SPWM, $V_{geon} = 15 \text{ V}$ $V_{geoff} = 0 \text{ V}$

$R_{gon} = 137 \text{ ohms}$

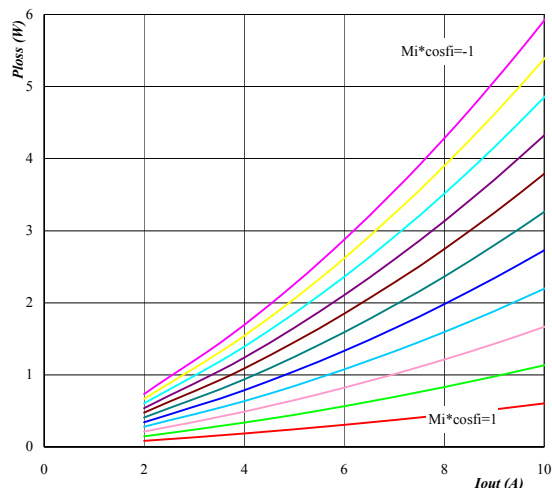
$R_{goff} = 68,5 \text{ ohms}$

Figure 1. Typical average static loss as a function of output current
IGBT $P_{loss} = f(I_{out})$



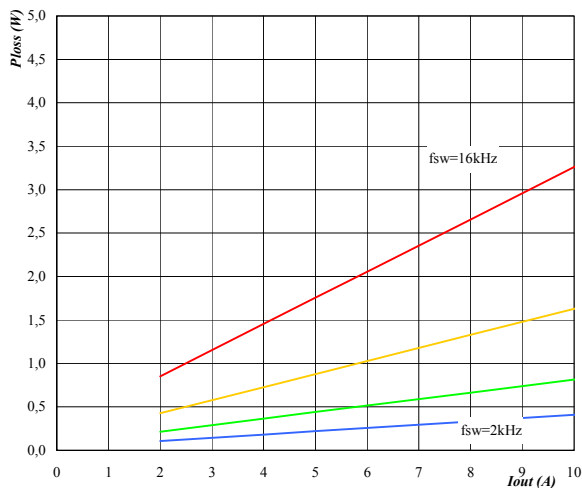
Conditions: $T_j = 125^\circ\text{C}$
Modulation index * cosfi
parameter $M_i \cdot \cos \phi_i$ from -1,00 to 1,00
in 0,20 steps

Figure 2. Typical average static loss as a function of output current
FRED $P_{loss} = f(I_{out})$



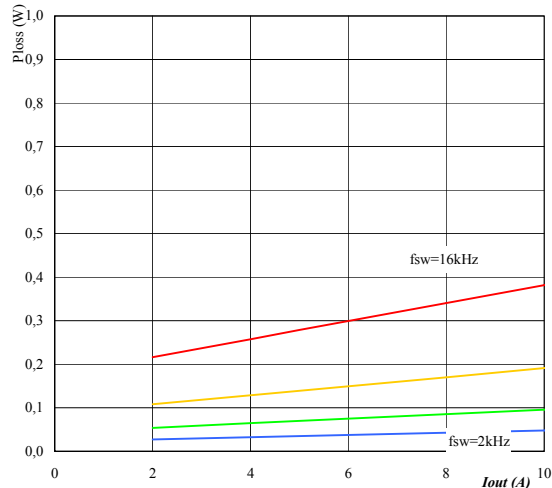
Conditions: $T_j = 125^\circ\text{C}$
Modulation index * cosfi
parameter $M_i \cdot \cos \phi_i$ from -1,00 to 1,00
in 0,20 steps

Figure 3. Typical average switching loss as a function of output current
IGBT $P_{loss} = f(I_{out})$



Conditions: $T_j = 125^\circ\text{C}$
DC link= 320 V
Switching freq. f_{sw} from 2 kHz to 16 kHz
parameter in * 2 steps

Figure 4. Typical average switching loss as a function of output current
FRED $P_{loss} = f(I_{out})$



Conditions: $T_j = 125^\circ\text{C}$
DC link= 320 V
Switching freq. f_{sw} from 2 kHz to 16 kHz
parameter in * 2 steps

Output inverter application

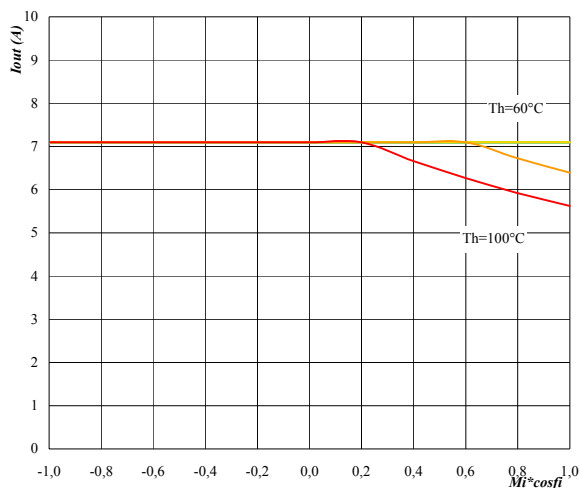
General conditions: 3 phase SPWM, $V_{geon} = 15 \text{ V}$ $V_{geoff} = 0 \text{ V}$

$R_{gon} = 137 \text{ ohms}$

$R_{goff} = 68,5 \text{ ohms}$

Figure 5. Typical available 50Hz output current as a function of $M_i \cdot \cos \phi_i$

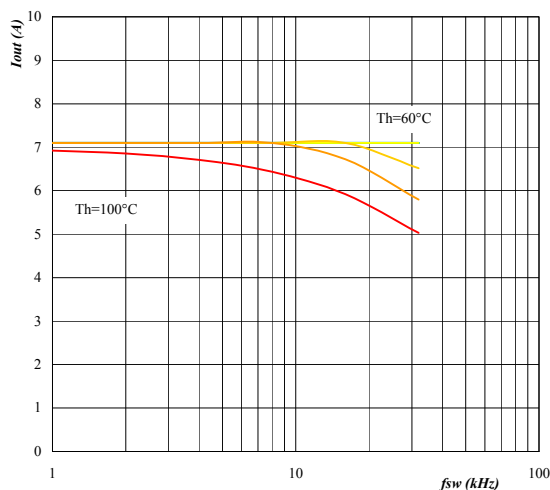
Phase $I_{out} = f(M_i \cdot \cos \phi_i)$



Conditions: $T_j = 125^\circ\text{C}$
 DC link= 320 V
 $f_{sw} = 16 \text{ kHz}$
 Heatsink temp. T_h from 60 °C to 100 °C
 parameter in 5 °C steps

Figure 6. Typical available 50Hz output current as a function of switching frequency

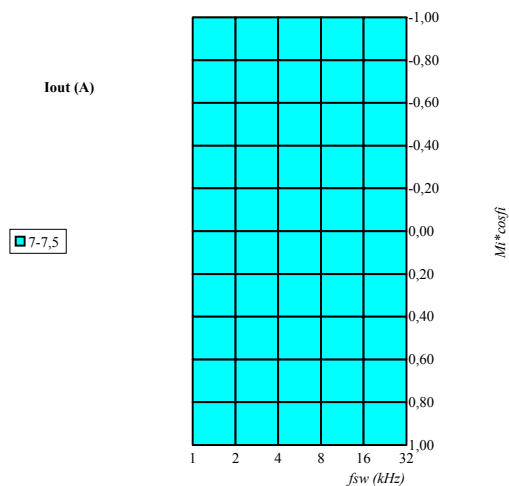
Phase $I_{out} = f(f_{sw})$



Conditions: $T_j = 125^\circ\text{C}$
 DC link= 320 V
 $M_i \cdot \cos \phi_i = 0,8$
 Heatsink temp. T_h from 60 °C to 100 °C
 parameter in 5 °C steps

Figure 7. Typical available 50Hz output current as a function of $M_i \cdot \cos \phi_i$ and f_{sw}

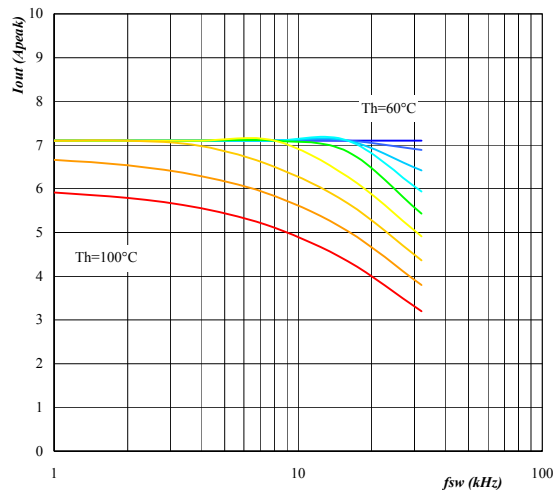
Phase $I_{out} = f(f_{sw}, M_i \cdot \cos \phi_i)$



Conditions: $T_j = 125^\circ\text{C}$
 DC link= 320 V
 $T_h = 80^\circ\text{C}$

Figure 8. Typical available 0Hz output current as a function of switching frequency

Phase $I_{outpeak} = f(f_{sw})$



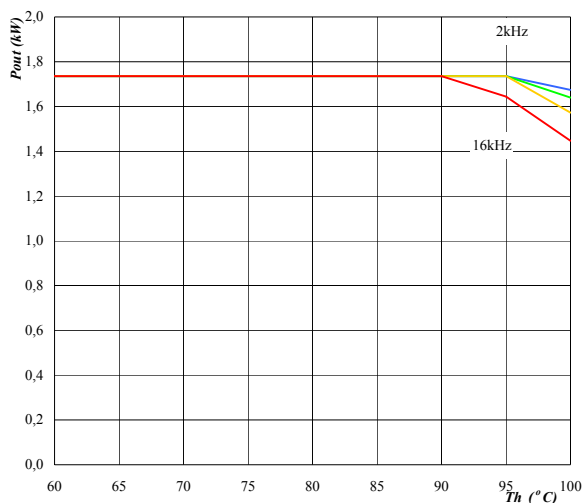
Conditions: $T_j = 125^\circ\text{C}$
 DC link= 320 V
 Heatsink temp. T_h from 60 °C to 100 °C
 parameter in 5 °C steps

Output inverter application

General conditions: 3 phase SPWM, $V_{geon} = 15 \text{ V}$ $V_{geoff} = 0 \text{ V}$ $R_{gon} = 137 \text{ ohms}$ $R_{goff} = 68,5 \text{ ohms}$

Figure 9. Typical available electric peak output power as a function of heatsink temperature

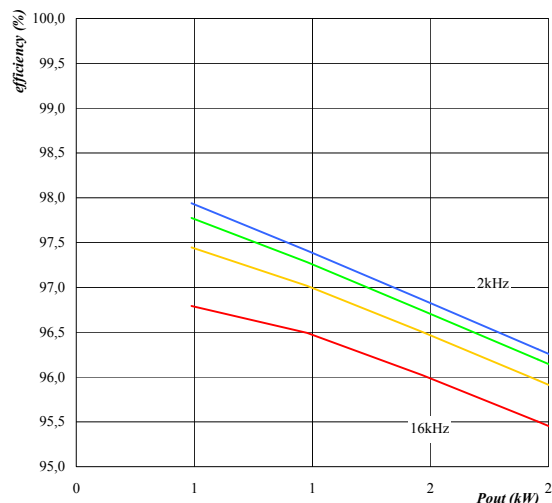
Inverter $P_{out} = f(T_h)$



Conditions: $T_j = 125^\circ\text{C}$
 DC link = 320 V
 Modulation index $M_i = 1$
 $\cos\phi_i = 0,80$
 Switching freq. parameter f_{sw} from 2 kHz to 16 kHz in * 2 steps

Figure 10. Typical efficiency as a function of output power

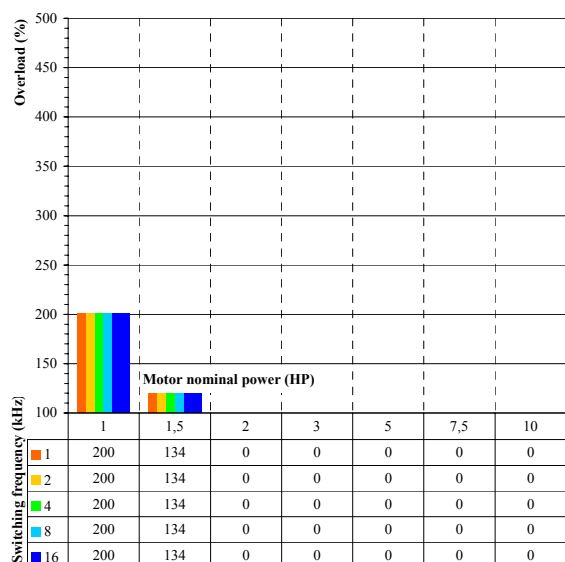
Inverter $\text{efficiency} = f(P_{out})$



Conditions: $T_j = 125^\circ\text{C}$
 DC link = 320 V
 Modulation index $M_i = 1$
 $\cos\phi_i = 0,80$
 Switching freq. parameter f_{sw} from 2 kHz to 16 kHz in * 2 steps

Figure 11. Typical available overload factor as a function of motor power and switching frequency

Inverter $P_{peak}/P_{nom} = f(P_{nom}, f_{sw})$



Conditions: $T_j = 125^\circ\text{C}$
 DC link = 320 V
 Modulation index $M_i = 1$
 $\cos\phi_i = 0,8$
 Switching freq. parameter f_{sw} from 1 kHz to 16 kHz in * 2 steps
 Heatsink temperature = 80°C
 Motor efficiency = 0,85